

Features

- Low current rectification
- Low forward voltage
- **SOD-923** Micro SMD package (Fig-1) Dimensions:
1.0 mm x 0.6 mm (0.039" x 0.024")
- RoHS compliant
- UL-94 V-0 / Green EMC
- Matte Tin Lead finish (Pb-Free)
- Moisture Level Sensitivity 1
- Cathode Band / Device marking:

Device Marking Code	
	F
L = Date Code*	



Fig -1 Package **SOD-923**

Absolute Maximum Ratings (Ta = 25 °C)

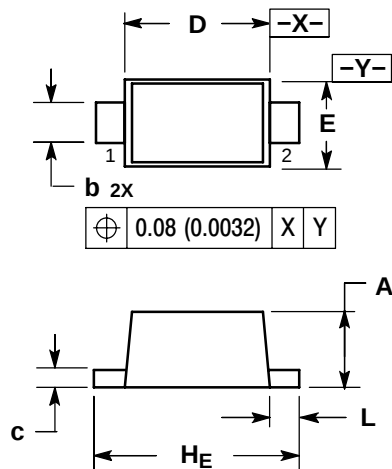
Symbol	Parameter	Value	Units
VRRM	Repetitive Peak Reverse Voltage	40	V
VR	Reverse Voltage	40	V
Io	Continuous Forward Current	200	mA
IFSM	Non-Repetitive Peak Forward Current *1	500	mA
TJ	Junction Temperature	125	°C
TSTG	Storage Temperature	-55 to +125	°C

*1: 8.3ms Single Half Sine-Wave

Electrical Characteristics (Ta = 25 °C)

Parameter	Symbol	Conditions	TYP	MAX	Units
Breakdown Voltage	V _{BR}	I _R =30μA	40	--	V
Forward Voltage	V _{F1}	I _F =10mA	0.3	0.38	V
	V _{F2}	I _F =100mA	0.45	0.8	V
					V
					V
Reverse Current	I _{R1}	V _R =10V	1.8	0.5	μA
	I _{R2}	V _R =20V	0.28	10	μA
	I _{R3}	V _R =30V	0.64	20	μA

SOD-923

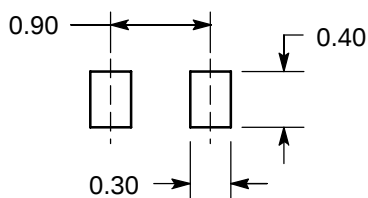


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.34	0.37	0.40	0.013	0.015	0.016
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
H _E	0.95	1.00	1.05	0.037	0.039	0.041
L	0.05	0.10	0.15	0.002	0.004	0.006

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

Ordering Information

Device	Package	Shipping	Tape wide	Embos pitch	Tape specification	Notes
KLM631CS-40	SOD-923	8,000 pcs / 7" Reel	8 mm	2 mm	Conductive	